課程資訊 (Course Information)					
科號	10810COM 524200	學分	3	人數限制	60
Course Number	10010COW 324200	Credit	β	Class Size	00
中文名稱	晶片應用系統簡介				
Course Title					
英文名稱					
Course English Introduction to System-on-Chip and its Applications					
Title					
任課教師	邱瀞德(CHIU, CHING-TE)				
Instructor	more information				
上課時間	M3M4W3	上課教室	EECS資電 129		
Time		Room			

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■發掘、分析、解決問題與獨立研究之能力 (20%)

The ability to discover, analyze, solve problems and to research independently. (20%)

■ 通訊科技整合與創新之能力 (20%)

此科目對應之系 所課程規畫所欲 培養之核心能力

Core capability

by this course

The ability to integrate and innovate communication technology. (20%)

■學習新知識與技術之能力 (20%)

The ability to learn new knowledge and techniques. (20%)

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The ability to communicate and express oneself effectively and to be proficient in foreign languages. (20%)

■具團隊精神及遵守專業倫理 (20%)

The ability to possess team spirit and to comply with professional ethics. (20%)

課程簡述 (Brief course description)

This course introduces what is System-on-Chip (SoC), benefits of using SoC, system architecture, design methodology and its applications. It uses several SoC designs, such as computer chip sets, cell phone IC, multimedia ICs, wireless communication ICs, information appliances and interface ICs, as examples to illustrate the top-down IC design flow, Intellectual Property(IP), system platform design and their market applications. The computer chip sets covers personal computer architectures, memory and peripheral I/O interface chip design. The cell phone IC covers heterogeneous multi-processor (HMP). The wireless communication includes CDMA, OFDM and LTE, 4G and 5G chip designs. The multimedia ICs covers audio, still image, and video, AR/VR ICs. The biomedical ICs covers Gene chip, Lab on a chip, and Ink-jet microarray. Emerging applications related SoC include autonomous vehicles, high resolution display, Internet of Things (IoT), 3D sensing, and deep learning acc

課程大綱 (Syllabus)

## Course keywords:

System-on-Chip (SoC), computer chip sets, cell phone IC, multimedia ICs, wireless communication ICs, information appliances and interface ICs

觀看上傳之檔案(.pdf) (若無法直接開啟,請按右鍵,選擇<另存目標>後再行查閱)

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